



CERAMIC DISC CAPACITOR SAFETY RECOGNIZED, AC SERIES (Small Size)

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# PRODUCT SPECIFICATION

PRODUCT: CERAMIC DISC CAPACITOR SAFETY RECOGNIZED For PITCH:5mm

TYPE: AC SERIES	
CUSTOMER:	
DOC. NO.: <u>POE-D12-00-E-24</u>	
Ver.: 24	

# APPROVED BY CUSTOMER

# **VENDOR:**

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#### MAKER:

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# CERAMIC DISC CAPACITOR SAFETY RECOGNIZED, AC SERIES(pitch5mm)

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**Record of change (continue)** 

Date	Version	Description	page
2008/6/3	1	1.D24-00-E-01( before) → POE-D12-00-E-01(1st edition)	
2009/9/22	2	1.Complete lead code	19
2008/8/22	2	2.Add last SAP code "H" for halogen and Pb free, epoxy resin	3
2009/12/12	2	1.Complete the 13th to 17th codes of SAP P/N.	4
2008/12/12	3	2.Page layout adjustment.	
		1. Change PSA & POE logo to Walsin & POE logo.	
		2. Complete Marking statement.	9
2009/7/16	4	3. Revised standard NO. of SEV, SEMKO, FIMKO, NEMKO, DEMKO and KEMA.	11
		4. Revised recognized NO. of FIMKO, NEMKO, DEMKO ,KEMA and CQC.	
		5. Downsize:	6
2009/9/14	5	1. Protrusion length: "1.0" maxrevised to "2.0max (Or the end of lead wire may be inside the tape.)"	8
		1. Delete the P/N of diameter above 10 mm.	6
2009/12/24	6	2. Marking	9
2009/12/24	0	3. Correct recognized No	10
		4. Revised the Figure of impulse voltage test(Item 7.3.14) according to the standard IEC 60384-14 ed.3	14
		1. Review SAP P/N about diameter code:	6
2011/1/13	7	2. Delete "AT" taping type.	4,5,8
2011/1/13	/	3. Add test item "Temperature Cycle".	15
		4. Add item 10 "Drawing of internal structure and material list"	20
		1. Add "1AC"type;	4
2011/5/13	8	2. Define the marking of the type "0AC" and "1AC";	9
2011/3/13	0	3. Delete "old P/N"	6~8
		4. Revie w the "Standard No. & Subclass & W.V. & Recognized No".	10
		1. Review the "Standard No. & Subclass & W.V. & Recognized No".	9
2012/2/7	9	2. Review the "Operating Temperature Range" from "-25 to +125°C" to "-40 to +125°C"	10
		3. Review the temperature of Step 1 from "-25+0/-3" to "-40+0/-3"	14
2012/4/6	10	In order to improve the traceability of the product, change the date code on capacitor body, new date code can trace back to production "Lot No."	8
		<u> </u>	5,6,7
		1. Review the Lead diameter φ from 0.60 +0.1/-0.05mm to 0.55+/-0.05mm	
2013/5/6	11	2. In order the customer to know the round time of manufacture, review the date code on capacitor body, new date code can know the month of manufacture.	8
2013/3/0	11	3. Delete "No marked with "_" stand for Pb free". Add "epoxy resin"	8
		4. Review the Solderability time from 2±0.5s to 5±0.5s	11
		1. Review the "Manufactured Date" to "Products ID" on the marking page	8
		2. Delete "The marking can be printed on either one side or two side of coating body." and add "for SAP	8
2013/10/16	12	part number 10-11 digits ≤ '07' products" to two sides and "for SAP part number 11-12 digits ≥	
		'08' products'' to one side.	
		1. Review the terminal position of the lead wire.	7
2014/11/5	13	2. Review the product of ID, add the code "D" for the products of Dongguan Walsin Technology	8
		Electronics Co., Ltd.	
2016/1/27	1.4	1. Review the Available lead code of Lead Configuration	5
2016/1/27	14	2. Revised standard NO. of VDE, SEV, SEMKO, FIMKO, NEMKO and DEMKO.	9
		1. Delete 6 pF~10 pF for P/N CH*AC***D06 * * , 12 pF~15 pF for P/N CH*AC120J06 * * ,18 pF~24	
2016/5/3	15	pF for P/N CH*AC***J07**, 27 pF~33 pF for P/N CH*AC***J08**, and 36 pF~39 pF for P/N	6
2016/11/2	1.0	CH*AC***J09**.	4 6 10 14 10
2016/11/3	16	1. Delete "CH" series.	4,6,10~14,19
2017/6/26	17	1. Revise CQC Standard No.	9
2018/8/11	18	1. Revised standard NO. of VDE, SEV, SEMKO, FIMKO, NEMKO and DEMKO.	9
		1. Protrusion length": "2.0max (Or the end of lead wire may be inside the tape.)" revised to	7
2019/4/25	19	"+0.5to-1.0 (Or the end of lead wire may be inside the tape.)"	7
		2. Add "Soldering Recommendation"	19
2019/12/11	20	1. Review the Available lead code of Lead Configuration	5
		2. Add "8.3 Label samples"	14
2021/9/9	21	1. Delete Walsin & POE logo.	1



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# **Record of change (continue)**

Date	Version	Description						
2022/4/20	22	<ol> <li>Add Applied voltage in 9.1 Caution (Rating):</li> <li>Add 9.3.4 List of substances that affect the insulation strength of coating</li> </ol>	16 18					
2023/5/26	23	Revised recognized No. of SEMKO and FIMKO.	9					
2023/9/25	24	1. Review the bulk packing quantity of the code of 14th to15th ≥12	14					

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# 1. Part number for SAP system

(Ex.)  $\underline{YV}$   $\underline{OAC}$   $\underline{472}$   $\underline{M}$   $\underline{10}$   $\underline{0}$   $\underline{L}$   $\underline{20}$   $\underline{C}$   $\underline{5}$   $\underline{H}$  (1) (2) (3) (4) (5) (6) (7) (8) (9) (10) (11)

# (1) Temperature characteristic (identified code)

CODE	Temperature characteristic	Cap. Change
SL	SL	-1000~+350ppm/°C (+20°C~+85°C)
YP	Y5P	±10%
YU	Y5U	-55% to +20%
YV	Y5V	-80% ~ +30%

(2) TYPE (identified by 3-figure code): 0AC = X1:400Vac/Y2:250Vac

(3)Capacitance (identified by 3-figure code) : EX.221=220pF

(4)Capacitance tolerance (identified by code) :  $J:\pm 5\%, K:\pm 10\%, M:\pm 20\%$ 

(5)Nominal body diameter dimension (identified by 2-figure code): 06--Dmax7.0mm, 07--Dmax8.0mm...

(6)Internal code: 0--Normal, other code--Special control

(7) Lead Style: Refer to "2. Mechanical".

(8) Packing mode and lead length (identified by 2-figure code)

Taping Code	Description	
AN	Ammo box and product pitch:	12.7mm
AM	Ammo box and product pitch:	25.4 mm

Bulk Code	Description				
03	Lead length: 3.0mm				
3E	Lead length: 3.5mm				
04	Lead length: 4.0mm				
4E	Lead length: 4.5mm				
20	Lead length: 20.0mm				

# (9) Tolerance of lead length

Code	Description						
A	±0.5 mm (only for kink lead type)	Short lead					
В	±1.0 mm	Short lead					
С	Min.	Long lead					
D	Taping special purpose	Taping					

### (10) Lead space

Code Description					
5	$5.0 \pm 0.8$ (For Bulk)				
	5.0+0.8/-0.2mm(For Taping)				
Е	$5.0 \pm 0.5$ mm				

# (11) Epoxy resin code

Code	Description
В	Halagan and Dh frag anavy rasin
Н	Halogen and Pb free, epoxy resin.



### 2. Mechanical

Encapsulation: Epoxy resin, flammability UL94 V-0

Available lead code: (unit: mm)

11 valiable lea	Available lead code: (unit: mm)						
Lead type	SAP P/N (13-17)digits	Lead space (F)	Lead Length (L)	Packing	Lead Configuration		
	L03B5		3.0 ± 1.0		D max. T max.		
Lead style: L	L3EB5		3.5 ± 1.0	Bulk			
Type L Straight long lead	L4EB5	$5.0 \pm 0.8$	4.5 ± 1.0				
Straight foligicat	L20C5		20 min.	Ø d-+ L			
Lead style: B	BAND5	50.00/02	Refer to "4.	m .	D max.		
Type B Straight long lead	BAMD5	5.0+0.8/-0.2	Taping format"	Tap. Ammo	e   F		
	D03A5		$3.0 \pm 0.5$		D max.		
Lead style: D	D3EA5	$5.0 \pm 0.8$	$3.5 \pm 0.5$	Bulk			
	D04A5		$4.0\pm0.5$				
Type D  Vertical kink lead	DAND5		Refer to "4.		+ + + + + + + + + + + + + + + + + + +		
Vertical Kilk lead	DAMD5	5.0+0.8/-0.2	Taping format"	Tap. Ammo	Ø d+		
	X03A5		$3.0 \pm 0.5$		D max. T max.		
	X3EA5	$5.0 \pm 0.8$	$3.5 \pm 0.5$	Bulk			
Lead style: X  Type X  Outside kink lead	X04A5		$4.0 \pm 0.5$				
	XAND5				× i		
	XAMD5	5.0+0.8/-0.2	Refer to "4. Taping format"	Tap. Ammo	Signal of the state of the stat		

<sup>\*</sup> Lead diameter Φd: 0.55 +/-0.05mm

<sup>\*</sup> **Coating extension** on leads): 3.0mmMax for straight lead lead style; Not exceed the kink for kink lead.





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3. Part numbering/T.C/Capacitance/ Tolerance/Diameter:

	Dimensions (unit: mm)								
SAP P/N	T.C.	Capacitance	Tolerance	_		111011310113	F		
		1		D	T	Bulk	Taping	φd	
				(max)	(max)	type	type		
SL*AC***J060*	SL	10,12,15,18,20,22,2 4,27,30,33, 36,39,47,50,51(pF)	±5%	7.0			•		
SL*AC***J070*		56,62, 68,75(pF)	±5%	8.0					
SL*AC820J080*		82pF	±5%	9.0					
SL*AC101J090*		100pF	±5%	10.0					
YP*AC101K060*		100 pF	±10%	7.0			5.0+0.8/-0.2 (AND5)		
YP*AC151K060*		150 pF	±10%	7.0			(AND3)		
YP*AC221K060*	VED	220 pF	±10%	7.0					
YP*AC331K060*	Y5P	330 pF	±10%	7.0	5.0	50100		0.55±0.05	
YP*AC471K060*		470 pF	±10%	7.0	3.0	5.0±0.8		0.33±0.03	
YP*AC561K070*		560 pF	±10%	8.0					
YP*AC681K070*		680 pF	±10%	8.0					
YP*AC821K080*		820 pF	±10%	9.0					
YP*AC102K080*		1000 pF	±10%	9.0					
YU*AC102M060*		1000 pF	±20%	7.0					
YU*AC152M080*	37511	1500pF	±20%	9.0					
YU*AC222M080*	Y5U	2200 pF	±20%	9.0					
YU*AC332M100*		3300 pF	±20%	11.0			50.00/0 <b>2</b>		
YU*AC392M120*		3900 pF	±20%	13.0			5.0+0.8/-0.2 (AMD5)		
YU*AC472M120*		4700 pF	±20%	13.0			(MINDS)		
YV*AC102M060*		1000 pF	±20%	7.0					
YV*AC152M060*	Y5V	1500 pF	±20%	7.0			5.0+0.8/-0.2		
YV*AC222M060*		2200 pF	±20%	7.0			(AND5)		
YV*AC332M080*		3300 pF	±20%	9.0					
YV*AC392M100*		3900 pF	±20%	11.0			<b>-</b> 0 0 0 / 0 -		
YV*AC472M100*		4700 pF	±20%	11.0			5.0+0.8/-0.2		
YV*AC682M120*		6800 pF	±20%	13.0			(AMD5)		
YV*AC103M140*		10000 pF	±20%	15.0					

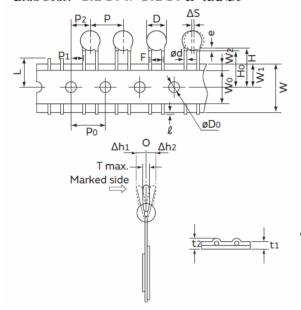
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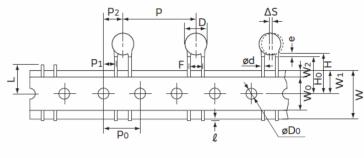
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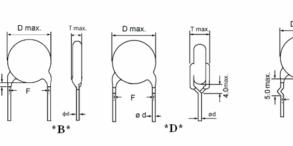
# 4. Taping Format:

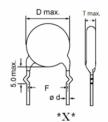
• 12.7mm pitch/lead spacing 5mm taping Lead Code: \*BAND5 & \*DAND5 & \*XAND5



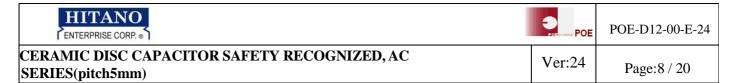
• 25.4mm pitch/lead spacing 5mm taping Lead Code: \*BAMD5 & \*DAMD5 & \*XAMD5







POE Part Number		*BAND5 *DAND5 *XAND5	*BAMD5 *DAMD5 *XAMD5	
Item	Symbol	Dimensions (mm)	Dimensions (mm)	
Pitch of component	P	12.7	25.4	
Pitch of sprocket	P0	12.7±0.3	12.7±0.3	
Lead spacing	F	5.0+0	.8/-0.2	
Length from hole center to component center	P2	6.35±1.5	$12.7 \pm 1.5$	
Length from hole center to lead	P1	3.75±1.0	10.2±1.0	
Body diameter	D	See the "3. Part numbering/T.C/C	apacitance/ Tolerance/Diameter"	
Deviation along tape, left or right	$\triangle S$	0±	2.0	
Carrier tape width	W	18.0 +	-1/-0.5	
Position of sprocket hole	W1	9.0-	±0.5	
Lead distance between the kink and center of sprocket hole	Н0	18.0+2.0/-0 (For: *DAND5 / *XAND5)	18.0+2.0/-0 (For: *DAMD5 / *XAMD5)	
Lead distance between the bottom of body and the center of sprocket hole	Н	20.0+1.5/-1.0 (For: *BAND5)	20.0+1.5/-1.0 (For: *BAMD5)	
Length from the terminal of the lead wire to the edge of carrier tape	$\ell$	+0.5 to -1.0 (Or the end of lead wire	may be inside the hole-down tape.)	
Diameter of sprocket hole	D0	4.0	±0.2	
Lead diameter	φd	0.55=	±0.05	
Total tape thickness	t1	0.6	±0.3	
Total thickness, tape and lead wire	t2	1.5 ɪ	nax.	
Deviation across tape	$\triangle h1/\triangle h2$	2.0 ɪ	nax.	
Portion to cut in case of defect	L	11.0	max.	
Hole-down tape width	W0	8.0	min	
Hole-down tape distortion	W2	3.0 max.		
Coating extension on leads	e	3.0 max for straight lead style; Not e	exceed the kink leads for kink lead.	
Body thickness	T	See the "3. Part numbering/T.C/C	apacitance/ Tolerance/Diameter"	



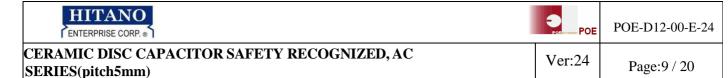
# 5. Marking:

1.Type De	esignation	AC							
2.Nominal	Capacitance	Identified by 3-Figure Code. Ex. 47pF "47", 470pF "471"							
3.Capacita	nce Tolerance	J:±5%,K:±10%,M:±20%							
4.Compan	y Name Code(Trade mark)	i K							
5.Manufac	ctured Date	Abbreviation ex.  Manufacture year:   1:2021  2:2022  3:2023  Manufactory:  C:Pan overseas (Guangzhou)  (Guangzhou)  Epoxy resin code:  "_": Haglogen and Pb free epoxy resin (For the last code "H" and "B" of SAP P/N)  SAP P/N)  Last 4 digits of lot no.  1:January 2:Feruary  9:September  O:October  N:November  D:December							
6.Approve	ed monogram:								
6.1 VDE	To OPE OF	6.3 CSA		6.5 NEMKO	$\bigcirc$	6.7 FIMKO	FI	6.9 CQC	Cec
6.2 UL	<i>FLI</i>	6.4 SEMKO	(3)	6.6 DEMKO	<b>(</b>	6.8 SEV	(\$)		
	Туре	( for S		wo sides mark	_	roducts)	( for S.	e side mar AP part numb s ≥"08" produ	er 11-12
Marking Ex.:	0AC (X1:400Vac/ Y2:250Vac)	Compared to 11 digits ≥ "08" products   digits ≥ "08" products						\$	

The marking shall be easily legible.

\*"C", Marked with code "\_" stand for Halogen and Pb free epoxy resin.

\*".": Individual specification code, it is added under the lot no.



# 6. Scope

THIS SPECIFICATION APPLIES TO CERAMIC INSULATED CAPACITORS DISK TYPE USED IN ELECTRONIC EQUIPMENT.

- 1. VDE/SEV/SEMKO/FIMKO/NEMKO/DEMKO/UL/CSA recognized capacitor for Antenna couplingand AC line-by-pass.X1, Y2 Capacitor based on IEC 60384-14 "UL, CSA recognized for across-the-line, line-by-pass" and antenna-isolation
- 2. Approval Standard and Recognized No.

Safety Standard	Standard No.	Subclass	w.v.	Recognized No.
UL	ANSI/UL 60384-14:2013	X1	400VAC	E146544
OL	ANSI/UL 00304-14.2013	Y2	250VAC	E140544
CSA	CAN/CSA E60384-14:2009	X1	400VAC	2347969
CSA	CAN/ C3A L00384-14.2009	Y2	250VAC	2347909
VDE	EN 60384-14:2013/A1:2016	X1	400VAC	40004.020
(ENEC)	IEC 6.384-14:2013 IEC 6.384-14:2013/AMD1:2016	Y2	250VAC	40001829
CE) /	EN 00004 44:0040 - 44:40	X1	400VAC	24.0555
SEV	EN 60384-14:2013 + A1:16	Y2	250VAC	21.0555
SEMKO	EN 60384-14:2013+A1	X1	400VAC	SE-S-1811994R1
SEIVINO	EN 00364-14.2013+A1	Y2	250VAC	3E-3-1611994K1
FIMKO	EN 60384-14:2013 + A1:16	X1	400VAC	FI/41696
FIIVIKO	EN 00384-14.2013 + A1.10	Y2	250VAC	FI/41090
NEMKO	EN 60384-14:2013;A1	X1	400VAC	P18222947
NEIVIKO	LN 00304-14.2013,A1	Y2	250VAC	F 10222347
DEMKO	EN 60384-14:2013/A1:2016	X1	400VAC	D-07617
DEIVINO	EN 60384-14:2013	Y2	250VAC	D-07017
CQC	GB/T6346.14-2015		400VAC :250VAC	CQC08001026519
KTL	K60384-14 2006	X1	400VAC or 440VAC	SU03065-14001
		Y2	250VAC	SU03065-14002



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# 7. Specification and test method:

### 7.1 Operating Temperature Range:

-40 to +125 °C

#### 7.2 Test condition:

Test and measurement shall be made at the standard condition. (temperature 15~35°C, relative humidity 45~75% and atmospheric pressure 860~1060hpa). Unless otherwise specified herein.

If doubt occurred on the value of measurement, and measurement was requested by customer capacitors shall be measured at the reference condition. (temperature 20±2°Cor25 ± 2°C, relative humidity 60~70% and atmospheric pressure 860~1060hpa.)

#### 7.3 Performance:

Item				Specification	<b>Testing Method</b>						
		Between lead wires		No failure.			ll not be	damage	when AC	C2000V a	rrent < 50mA.)
1	Dielectric Strength	Body Insulation		No failure.	First, the terminals of the capacitor should be connected together.  Then, a metal foil should be closely wrapped around the body of the capacitor to the distance of about 3 to 6mm from each terminal. Then, the capacitor should be inserted into a container filled with metal balls of about  Imm diameter.Finally, AC2000V (r.m.s.)<50/60Hz> is applied for 60 s between the capacitor lead wires and metal balls. (Charge/Discharge current ≤ 50mA.)  The insulation resistance shall be measured with 500±50VDC with						
2	Insulation Resis	tance(I.R.)	10000M	Ω min.	The insula 60±5sec.			hall be m	easured v	w1th 500±	-50VDC with
3	Capacitance		Within sp	pecified tolerance	Y5P&Y5U	J&Y5V:	The ca	pacitance	shall be	measure	ed at 20±2°C with
			Char.	Specification	1kHz±20%	6 and 1.0	Vrms				
	Dissipation Factor(D.F.) or Q		Y5P Y5U Y5V	D.F≦2.5% D.F≦5.0%	SL: The capacitance shall be measured at 25°C with 1MHz±20% and1.0Vrms						1MHz±20%
4			SL	Q: 30pF&above:≥1000 Below 30PF:≥400+20×C							
			Char.	Capacitance Change	The capacitance measurement shall be made at each step specified in table						
			Y5P	Within ± 10%	Step	1	2	3	4	5	
5	Temperature Char	racteristic	Y5U	Within ± 5 5 %	Temp.(°C)	+20±2	-25±2	+20±2	+85±2	+20±2	
			Y5V	Within -80 ~ +30%						<u> </u>	
			SL	-1000~+350 ppm/°C (+20°C~+85°C)	Pr-treatme Capacitor condition		stored at )24±2 ho	: 125±2°C ours before	C for 1 hore measur	our. Then rement	placed at room
		Tensile		e shall not cut off shall not be broken.	As shown capacitor lead wire up to 10N	and appl	y a tensi dial direc	le weight ction of the	graduall	y to each	M M
6	Robustness of Termination Bending			e shall not cut off shall not be broken.	up to 10N and keep it for $10\pm1$ sec.  With the termination in its normal position the specimen is held by body in such a manner that the axis of the termination is vertical: a applying a force of 5N is then suspended from the end of the termination. The body of the specimen is then inclined within a pe 2 to 3 sec., through an angle of approximately 90° in the vertical p and then resumed to its initial position over the same period of time operation constitutes one bend. One bend immediately followed by a second bend in the opposite direction.			is vertical: a mass d of the d within a periodof the vertical plane period of time; this			

<sup>&</sup>quot;room condition" temperature: 15~35°C, humidity: 45~75%, atmospheric pressure: 86~106kPa

<sup>&</sup>quot;C" expresses nominal capacitance value (pF).





# CERAMIC DISC CAPACITOR SAFETY RECOGNIZED, AC SERIES(pitch5mm)

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	Item		Specification	<b>Testing Method</b>
7	Solderability	y of leads	Lead wire should be soldered with uniform coating on the axial direction over 3/4 of the circumferential direction.	The lead wire of capacitor should be dipped into molten solder for $5 \pm 0.5$ sec.  The depth of immersion is up to about 1.5 to 2.0 mm from the root of lead wires.  Temp. of solder : Lead free solder (Sn-3Ag $-0.5$ Cu) $245 \pm 5$ °C
		Appearance I.R. Dielectric	No marked defect $1000 \mathrm{M}\Omega$ min.	As shown in figure, the lead wires should be immersed in solder of $350 \pm 10$ °C or $260 \pm 5$ °C up to 1.5 to 2.0mm from the root of Terminal for $3.5 \pm 0.5$ sec ( $10 \pm 1$ sec for $260 \pm 5$ °C )
	Soldering Effect (Non-Preheat)	Strength  Capacitance Change	Y5P,Y5U,Y5V: Within ±10% SL: Within±2.5 % or ±0.25pF,Whichever is large.	Pre-treatment: Capacitor shall be stored at 125±2°C for 1hour.then placed at * ¹room condition for 24±2hours before initial measurements.  Post-treatment: Capacitor shall be stored for 1 to 2hours at * ¹room condition
8		Appearance	No marked defect.	First the capacitor should be stored at $120 + 0 / -5$ °C for $60 + 0 / -5$ sec.
		I.R.	1000MΩ min.	Then, as in figure , the lead wires should be immersed solder of $260 + / -5$ °C up to 1.5 to 2.0 mm from the root of terminal for 7.5 $+0 / -1$ sec.
	Soldering Effect (On-Preheat)	Dielectric Strength	Per Item 1.	Thermal Capacitar Screen 1.5  1.5  The trial Capacitar  And the Capacitar  And the Capacitar  And the Capacitar  Solder
	(On-Preheat)  Capacitance Change		Y5P,Y5U,Y5V: Within ±10% SL: Within±2.5 % or ±0.25pF,Whichever is large.	Pre-treatment: Capacitor shall be stored at 125±2°C for 1hour.then placed at **1room condition for 24±2hours before initial measurements.  Post-treatment: Capacitor shall be stored for 1 to 2hours at **1room condition

<sup>%</sup> "room condition" temperature: 15~35°C, humidity: 45~75%,atmospheric pressure: 86~106kPa

<sup>&</sup>quot;C" expresses nominal capacitance value (pF).





# CERAMIC DISC CAPACITOR SAFETY RECOGNIZED, AC SERIES(pitch5mm)

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Item			Specification	Testing Method				
9	Humidity (Under Steady State)	Appearance Capacitance Change	No marked defect.  Y5P: Within ±10% Y5U: Within ±20% Y5V: Within ±30% SL: Within ±2.5 % or ±0.25pF,Whichever is large.	Set the capacitor for 500±12 hours at 40±2°C, in 90 to 95% humidity.  Pre-treatment:  Capacitor shall be stored at 125±2°C for 1hour.then placed at * 1 room condition for 24±2hours before initial measurements.  Post-treatment:				
		D.F.	Y5P,Y5U: 5.0% max. Y5V: 7.5% max.	Capacitor shall be stored for 1 to 2hours at **1room condition.				
10	Humidity Loading	Q	SL: Q≥ 200 (C≥30pF) Q≥100+10×C/3(C < 30pF)	Apply the rated voltage for 500±12 hours at 40±2°C, in 90 to 95% humidity.  Pre-treatment:  Capacitor shall be stored at 125±2°C for 1hour.then placed at *1 room condition for 24±2 hours before initial measurements.				
		I.R.	Y5P,Y5U,Y5V: $3000$ M $\Omega$ min. SL: $1000$ M $\Omega$ min.	Post-treatment:  Capacitor shall be stored for 1 to 2hours at **1room condition.				
		Appearance	No marked defect.	Impulse Voltage: Each individual capacitor shall be subjected to a 5kv impulses for				
		Capacitance Change	Y5P,Y5U,Y5V: Within ±20% SL: Within±3 % or ±0.3pF,Whichever is large.	three times. After the capacitors are applied to life test. $ \begin{array}{c ccccccccccccccccccccccccccccccccccc$				
		I.R.	3000MΩ min. SL: $1000$ MΩ min.	95 8 5 Vp				
11	Life	Dielectric Strength	Per Item 1.	Fig.  The specimen capacitors are placed in a circulating air oven for a period of 1000 hrs. The air in the oven is maintained at a temperature of 125±2°C. Throughout the test. The capacitors are subjected to an AC425Vrms.(for 2AC type) or AC510Vrms.(for 3AC type) alternating voltage of mains frequency.  Pre-treatment:  Capacitor shall be stored at 125±2°C for 1hour.then placed at *1room condition for 24±2hours before initial measurements.  Post-treatment:  Capacitor shall be stored for 1 to 2hours at *1room condition.				

<sup>\* &</sup>quot;room condition" temperature: 15~35°C, humidity: 45~75%,atmospheric pressure: 86~106kPa

 $<sup>\</sup>mbox{\em $\mathbb{K}$}$  "C" expresses nominal capacitance value (pF).





# CERAMIC DISC CAPACITOR SAFETY RECOGNIZED, AC SERIES(pitch5mm)

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	Item		pecification			Testing Meth	od	
12	Active Flammability	tive The cheesesto	th shall not be on fire.					
13	Passive Flammability		me shall not be exceeded c. The tissue paper shall	The capacitor under test shall be held in the flame in the position, which best promotes burning. Each specimen shall only be exposed once to the flame.  Time of exposure to flame: 30 sec  Length of flame: 12±1 mm  Gas burner: Length 35 mm min.  Inside Dia.: 0.5±0.1 mm  Outside Dia.: 0.9 mm max.  Gas: Butane gas Purity 95% min.  **approxirasaly**  **8 mm**  **Test specimen**  206 ± 5 mm**				
		Appearance	No marked defect			e subjected to 5 tem		es,
		Char. Cap. Change	DF / Q	_	<ten Step</ten 	nperature Cycle time $^{\circ}$ C)	Time(min)	
		SL ≤±5%	$Q \ge 275 + 5/2C(C < 30pF)$ $Q \ge 350 (C \ge 30pF)$		1	-40+0/-3	30	
	Temperature	y5P ≤±10%	Q=530 (C=50pF) DF≤5.0%	_	2	Room temp.	3	
15	Cycle	I V5II I	DF≦7.5%		3	125+3/-0	30	
			2000MO:	Pre-treatment	4	Room temp.	3	
		I.R.  Dielectric strength	3000MΩ min.  Per Item 1	Pre-treatment:  Capacitor shall be stored at 125±2°C for 1hour.then placed at   room condition for 24±2hours.  Post-treatment:  Capacitor shall be stored for 1 to 2hours at   *1room condition.				

 $<sup>\,\,\%\,\,</sup>$  "room condition" temperature: 15~35°C, humidity: 45~75%,atmospheric pressure: 86~106kPa

 $<sup>\</sup>mbox{\em $\mathbb{K}$}$  "C" expresses nominal capacitance value (pF).





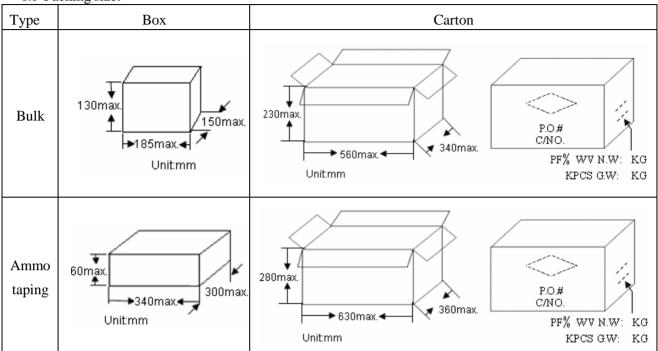
# CERAMIC DISC CAPACITOR SAFETY RECOGNIZED, AC SERIES(pitch5mm)

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# 8. Packaging Baggage:

8.1 Packing size:



8.2 Packing quantity:

8 1	· · · · <b>y</b> ·	
Packing type	The code of 14th to15th in SAP P/N	MPQ(Kpcs/Box)
	AN	1
Taping	AM (The size code ≤ 11)	1
	AM (The size code≥12)	0.5

Packing type	Lead length	Size code of 10th to 11th in SAP P/N	MPQ (Kpcs/Bag)	Kpcs/Box
	Long lead	06~12	0.5	1.5
Bulk	(L≧20mm)	13-14	0.5	1
	Short lead	06~12	0.5	2
	(L < 20mm)	13-14	0.5	1.5

8.3 Label samples:



#### 9. Notices:

### 9.1 Caution(Rating):

#### (1). Operating Voltage

Be sure to maintain the Vp-p value of the applied voltage or the Vo-p which contains DC bias within therated voltage range.

When the voltage is started to apply to the circuit or it is stopped applying, the irregular voltage may be generated for a transit period because of resonance or switching. Be sure to use a capacitor within rated voltage containing this irregular voltage.

Voltage	DC Voltage	DC+AC Voltage	AC Voltage
Positional measurement	V0-p	V0-p	Vp-p

### (2). Operating Temperature and Self-generated Heat

Keep the surface temperature of a capacitor below the upper limit of its rated operating temperature range. Be sure to take into account the heat generated by the capacitor itself.

### (3). Test condition for withstanding Voltage

### I. Test Equipment

Test equipment for AC withstanding voltage shall be used with the performance of the wave similar to 50/60 Hz sine waves.

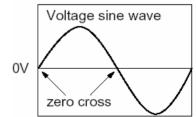
If the distorted sine wave or over load exceeding the specified voltage value is applied, the defective may be caused.

#### II. Voltage Applied Method

When the withstanding voltage is applied, capacitor's lead or terminal shall be firmly connected to the output of the withstanding voltage test equipment, and then the voltage shall be raised from nearzero to the test voltage.

If the test voltage without the raise from near zero voltage would be applied directly to capacitor,

test voltage should be applied with the \*zero cross. At the end of the test time, the test voltage shall bereduced to near zero, and then capacitor's lead or terminal shall be taken off the output of the withstanding voltage test equipment.



If the test voltage without the raise from near zero voltage would be applied directly to capacitor, the surge voltage may arise, and therefore, the defective may be caused.

ZERO CROSS is the point where voltage sine wave pass0V.- See the right figure.



### III. Applied voltage

The voltages of Table shall be applied between the respective measuring points of 1 min for qualification approval and periodic testing and for a period of not less than 1 s for lot-by-lot quality conformance testing, a voltage proof test such as Test C shall be carried out only for qualification approval tests and periodic tests;

Attention is drawn to the fact that repetition of the voltage proof test by the user may damage the capacitor. If repetition of the voltage proof test is made by the user, the applied voltage should not be greater than 66 % of the test voltage specified in Table .

Table -Voltage proof

Class	Range of rated voltages	Test A	Test B or Test C	
X1	≤ 1 000 V	4,3 UR (d.c.) c	2 UR + 1 500 V (a.c.) with a minimum of 2 000 V (a.c.) a	
Y2	≥ 150 V ≤ 500 V	UR + 1 200 V (a.c.) with a minimum of 1 500 V (a.c.) b	2 UR + 1 500 V (a.c.) with a minimum of 2 000 V (a.c.) b	

a For Delta and T-connected capacitor units according to Figures 5b and 5c, the test voltage for terminals to case shall be the appropriate test voltage for the Y-capacitors.

#### Note:

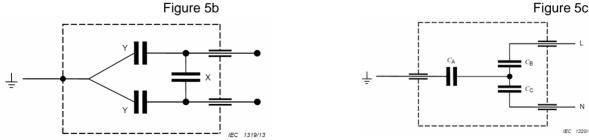
Test A – Between terminations

Test B - Internal insulation

Test C – External insulation (applicable only to insulated capacitors in nonmetallic case or in insulated metal case)

Figure 5b – Delta by-pass capacitor (in metallic housing)

Figure 5c – Example of a T-connected by-pass capacitor (in non-metallic housing)



\*For capacitors with non-metallic housings, the earth connection is brought out as a separate termination as is shown in Figure 5c.

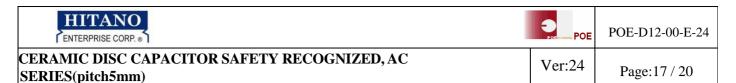
#### (4).Fail-Safe

When capacitor would be broken, failure may result in a short circuit. Be sure to provide an appropriate fail-safe function like a fuse on your product if failure would follow an electric shock, fire or fume.

Failure to follow the above cautions may result, worst case, in a short circuit and cause fuming or partial dispersion when the product is used.

<sup>&</sup>lt;sub>b</sub> For lot-by-lot tests of Class Y2 capacitors, the a.c. test voltage may be replaced by a d.c. voltage of 1,5 times the prescribed a.c. voltage.

c The UR in this d.c. test is the rated a.c. voltage value.



### **9.2** Caution (Storage and operating condition):

Operating and storage environment

The insulating coating of capacitors does not form a perfect seal; therefore, do not use or store capacitors in a corrosive atmosphere, especially where chloride gas, sulfide gas, acid, alkali, salt or the like are present. And avoid exposure to moisture. Before cleaning, bonding, or molding this product, verify that these processes do not affect product quality by testing the performance of a cleaned, bonded or molded product in the intended equipment. Store the capacitors where the temperature and relative humidity do not exceed -10 to 40 degrees centigrade and 15 to 85 % for 6 months maximum and use within the period after receiving the capacitors.

"Failure to follow the above cautions may result, worst case, in a short circuit and cause fuming orpartial dispersion when the product is used."

## 9.3 Caution (Soldering and Mounting):

#### 9.3.1 Vibration and impact:

Do not expose a capacitor or its leads to excessive shock or vibration during use.

#### 9.3.2 Soldering;

When soldering this product to a PCB/PWB, do not exceed the solder heat resistance specification of the capacitor. Subjecting this product to excessive heating could melt the internal junction solder and may result in thermal shocks that can crack the ceramic element.

When soldering capacitor with a soldering iron, it should be performed in following conditions.

Temperature of iron-tip: 400 degrees C. max.

Soldering iron wattage: 50W max.

Soldering time: 3.5 sec. max.

#### 9.3.3 Cleaning (ultrasonic cleaning):

To perform ultrasonic cleaning, observe the following conditions.

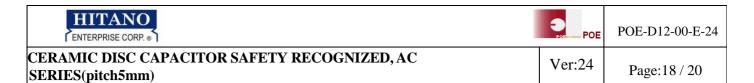
Rinse bath capacity: Output of 20 watts per liter or less.

Rinsing time: 5 min maximum.

Do not vibrate the PCB/PWB directly.

Excessive ultrasonic cleaning may lead to fatigue destruction of the lead wires.

"Failure to follow the above cautions may result, worst case, in a short circuit and causefuming or partial dispersion when the product is used."



# 9.3.4 List of substances that affect the insulation strength of coating:

**Epoxy resin solvent** 

<u> </u>						
Category	Model					
Ketone	Acetone	Butanone	Cyclohexanone			
Esters	Ethyl acetate	Dibutyl phthalate				
Chlorinated hydrocarbons	Dichloromethane					

Epoxy resin thinner

Epoxy resin thinner						
Category		Model				
Reactive diluentactivated thinner	Simple function group	HK-66 (Alkyl glycidyl ether)				
		501 (Butyl glycidyl ether)				
		690 (Phenyl Glycidyl Ether )				
		AGE (C12-14Aliphatic Polyalcohol Glycidyl Ether)				
		692 (Benzyl Glycidyl Ether)				
	Two functional groups	D-678 (Neopentyl glycol diglycidyl ether)				
		622 (1,4-Butanediol diglycidyl ether)				
		669 (Ethylene glycol diglycidyl ether)				
		X-632 (Polypropylene glycol diglycidyl ether)				
		X-652 (1,6-Hexadiol diglycidyl ether)				
		D-691Epoxypropane o-methylphenyl ether				
		Anhydrous	Toluene			
		ethanol	Totalene			
		Ethyl acetate	Dimethylbenzene			
Non-activated thin	ner	Dimethyl	Butyl acetate			
		formamide	Buty1 uccuite			
		Acetone	Styrene			
		Polyol	Benzyl alcohol			

Note: The above substances should not contact the coating of the product body, otherwise it will affect the insulation strength of the product

# 9.4 Caution (Handling):

Vibration and impact

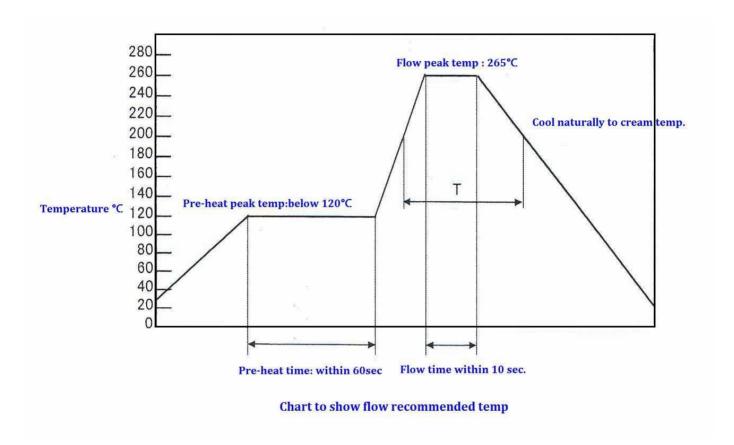
Do not expose a capacitor or its leads to excessive shock or vibration during use.

"Failure to follow the above cautions may result, worst case, in a short circuit and cause fumingor partial dispersion when the product is used."

# 10. Soldering Recommendation:

#### 10.1 Wave Soldering Profile:

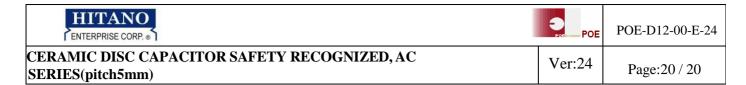
- Temperature conditions of the flow is recommended as shown in the chart
- Must implement the pre-heat
- Maximum peak flow temperature is recommended 265°C
- Time "T" implement in the chart recommended within 20 sec. it temperature exceed 200°C
- Take care with the flow solder not to touch the capacitor body directly at mounting



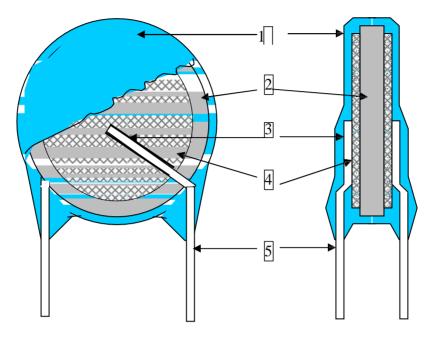
### 10.2 Recommended Reking Conditions with Soldering Iron:

- Temperature of iron-tip: 400 degrees C. max.
- Soldering iron wattage: 50W max.
- Soldering time: 3.5 sec. max.
- Distance from coating body: 2 mm (min.)

10.3 Reflow-Soldering: Lead Ceramic Cap. should not be soldered by reflow-soldering.



# 10. Drawing of internal structure and material list:



# Remarks:

No.	Part name	Material	Model/Type	Component
		T 1	EF-150	Epoxy resin. Pigment
1 Insulation Coating	Epoxy polymer	PCE-300	(Blue / UL 94 V-0)	
			ECP-357	(Blue / OL 94 V-0 )
2 Dielectric Elen		Ceramic	SL/Y5P/Y5U/Y5V	SL: SrCO3/TiO2/Bi2O3/CaCO3
	Dielectric Element			Y5P: BaTiO3/Bi2O3/SnO2/CeO2
				Y5U: BaTiO3/ZrO2/ CaCO3
				Y5V: BaTiO3/ WO3/ CeO2
3	Solder	Tin-silver	Sn96.5-Ag3-Cu0.5	Sn96.5-Ag3-Cu0.5
4	Electrodes	Ag	SP-160PL	Silver Glass frit
			SP-260PL	
5	Leads wire	Tinned copper clad	0.55±0.05 mm	Substrate metal: Fe & Cu
		steel wire		Surface plating: Sn 100%(3~7μm)